



## **ACM Research Adds Metal Lift Off Capability to Ultra C pr Tool to Support Power Semiconductor Manufacturing and Wafer Level Packaging Applications**

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### **First system qualified at power semiconductor manufacturer in China**

FREMONT, Calif., Nov. 11, 2022 (GLOBE NEWSWIRE) -- [ACM Research, Inc.](#) (ACM) (NASDAQ: ACMR), a leading supplier of wafer processing solutions for semiconductor and advanced wafer-level packaging (WLP) applications, today announced that it has expanded its Ultra C pr product offering to include metal lift-off (MLO) capabilities for power semiconductor manufacturing and wafer level packaging (WLP) applications. MLO can be used to save an etch process step, reducing cost, optimizing cycle times and sharply reducing chemical demand at high temperatures. The company also announced that the first MLO-capable Ultra C pr tool has been qualified and released to mass production at a power semiconductor manufacturer in China.

“ACM is committed to strengthen its position as a multi-product company, and we continue to extend our product offering to new opportunities beyond cleaning,” said Dr. David Wang, ACM’s President and Chief Executive Officer. “Our Ultra C pr tool has already achieved broad customer adoption due to its photoresist stripping capabilities. With MLO, our Ultra C pr tool now supports the lifting of metals off the photoresist, and the removal of any excess metals or residuals. We are excited with the successful qualification of ACM’s first Ultra pr tool with MLO capabilities, as an initial validation of the technology in a production environment.”

ACM addresses the complexities of the MLO application by leveraging the Ultra C pr’s unique combination of wet bench and single wafer manufacturing technology to deliver the high throughput of a batch tool as well as the superior removal performance of a single-chamber tool. It also features a dual filter system ensure optimal cleanliness during manufacturing. In addition, ACM SAPS megasonic technology can be configured for MLO to enhance cleaning performance for patterned or structured wafers.

#### **About ACM Research, Inc.**

ACM develops, manufactures and sells semiconductor process equipment for single-wafer or batch wet cleaning, electroplating, stress-free polishing and vertical furnace processes, which are critical to advanced semiconductor device manufacturing and wafer-level packaging. The company is committed to delivering customized, high-performance, cost-effective process solutions that semiconductor manufacturers can use in numerous manufacturing steps to improve productivity and product yield. For more information, visit [www.acmrcsh.com](http://www.acmrcsh.com).

#### **Forward-Looking Statements**

Information presented in this press release includes forward-looking statements for purposes of the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. All statements contained in this press release that do not relate to matters of historical fact should be considered forward-looking statements, including statements in the first, second, fifth and eighth paragraphs with respect to the preliminary expected revenue ranges of ACM Shanghai for the three and nine months ended September 30, 2022, backlog information for ACM Shanghai as of September 30, 2022 and the potential impacts of the new regulations of the U.S. Department of Commerce. The preliminary financial results and backlog information included in this press release are unaudited and remain subject to review and adjustment. Forward-looking statements are based on ACM management’s current expectations and beliefs, and involve a number of risks and uncertainties that are difficult to predict and that could cause actual results to differ materially from those stated or implied by the forward-looking statements. Those risks and uncertainties include, but are not limited to, the following, any of which could be exacerbated even further by the continuing COVID-19 outbreak in China and globally: anticipated customer orders or identified market opportunities may not grow or develop as anticipated; customer orders already received may be postponed or canceled; ACM may be unable to obtain the qualification and acceptance of its delivered tools when anticipated or at all, which would delay or preclude ACM’s recognition of revenue from the sale of those tools; suppliers may not be able to meet ACM’s demands on a timely basis; ACM’s technologies and tools may not gain market acceptance; ACM may be unable to compete effectively by, among other things, enhancing its existing tools, adding additional production capacity and engaging additional major customers; ACM may incur significant expenses long before it can recognize revenue from new products, if at all, due to the costs and length of research, development, manufacturing and customer evaluation process cycles; amounts included in backlog may not ultimately result in revenue; volatile global economic, market, industry and other conditions could result in sharply lower demand for products containing semiconductors and for ACM’s products and in disruption of capital and credit markets; ACM’s failure to successfully manage its operations, including its inability to hire, train, integrate and manage additional qualified engineers for research and development activities; and trade regulations, currency fluctuations, political instability and war may materially adversely affect ACM due to its substantial non-U.S. customer and supplier base and its substantial non-U.S. manufacturing operations. A further description of these risks, uncertainties and other

matters can be found in filings ACM makes with the U.S. Securities and Exchange Commission. Because forward-looking statements involve risks and uncertainties, actual results and events may differ materially from results and events currently expected by ACM. ACM undertakes no obligation to publicly update these forward-looking statements to reflect events or circumstances that occur after the date hereof or to reflect any change in its expectations with regard to these forward-looking statements or the occurrence of unanticipated events.

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